

# U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10074718	02/13/2002	228	41	1725	Cooper

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**\*\*CONTINUING DATA VERIFIED:**

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**\*\* FOREIGN APPLICATIONS VERIFIED:**  
JAPAN 2001-039888 02/16/2001

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

JP920000451US1

**TITLE :** Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

## NOTICE OF ALLOWANCE MAILED

Amount Due ☐ Date Paid

### ISSUE FEE

Amount Due ☐ Date Paid



TERMINAL

DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

## CLAIMS ALLOWED

Total Claims

Print Claim for  
O.G.

### DRAWING

Sheets Drawn

Figs. Drawn

Print Fig.

Application Examiner

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